

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L8	11	7 and ((silicon adj carbide) Sic)	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 17:58

L7	40	(US-20010026956-\$ or US-20020016085-\$ or US-20020108929-\$ or US-20030024902-\$ or US-20030045101-\$ or US-20030162407-\$).did. or (US-5021121-\$ or US-5269879-\$ or US-5843847-\$ or US-6074959-\$ or US-6090304-\$ or US-6117786-\$ or US-6153514-\$ or US-6207554-\$ or US-6207577-\$ or US-6211092-\$ or US-6251770-\$ or US-6284149-\$ or US-6297163-\$ or US-6316349-\$ or US-6326307-\$ or US-6368979-\$ or US-6376367-\$ or US-6380091-\$ or US-6387775-\$ or US-6395631-\$ or US-6410437-\$ or US-6417090-\$ or US-6451673-\$ or US-6455411-\$ or US-6472317-\$ or US-6485988-\$).did. or (US-6506680-\$ or US-6541396-\$ or US-6670276-\$ or US-6693042-\$ or US-6696366-\$ or US-6743732-\$ or US-6350674-\$).did. or (US-6472317-\$).did.	US-PGPU B; USPAT; DERWEN T	OR	OFF	2005/09/23 17:57
L6	24	(C5F8 "C.sub.5 F.sub.8") same (N2 "N.sub.2" nitrogen) same (ar argon) same etch\$3 not 3	US-PGPU B; USPAT	OR	ON	2005/09/23 16:35

L5	0	(C5F8 "C.sub.5 F.sub.8") with (N2 "N.sub.2" nitrogen) same (ar argon) same etch\$3 not 3	US-PGPU B; USPAT	OR	ON	2005/09/23 16:35
L3	14	(C5F8 "C.sub.5 F.sub.8") with (N2 "N.sub.2" nitrogen) with (ar argon) same etch\$3	US-PGPU B; USPAT	OR	ON	2005/09/23 16:34
L4	5	3 not 2	US-PGPU B; USPAT	OR	ON	2005/09/23 16:33
L2	9	(C5F8 "C.sub.5 F.sub.8") with (N2 "N.sub.2" nitrogen) with (ar argon) with etch\$3	US-PGPU B; USPAT	OR	ON	2005/09/23 16:33
L1	17148	(C5F8 "C.sub.5 F.sub.8") same (N2 "N.sub.2" nitrogen) (ar argon) same etch\$3	US-PGPU B; USPAT	OR	ON	2005/09/23 16:31
S63	24	((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane) same (CH2F2 CF2H2 "CH.sub.2 F.sub.2" "CF.sub.2 H.sub.2" difluoromethane) same (N2 "N.sub.2" nitrogen)) same etch\$3 not (S60 S61)	US-PGPU B; USPAT	OR	ON	2005/09/23 16:29
S60	13	((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane) with (CH2F2 CF2H2 "CH.sub.2 F.sub.2" "CF.sub.2 H.sub.2" difluoromethane) with (N2 "N.sub.2" nitrogen)) with etch\$3	US-PGPU B; USPAT	OR	ON	2005/09/23 02:54
S62	3	("6121145"   "6211092"   "6251789").PN. OR ("6506680").URPN.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/09/23 02:50

S61	5	((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane) with (CH2F2 CF2H2 "CH.sub.2 F.sub.2" "CF.sub.2 H.sub.2" difluoromethane) with (N2 "N.sub.2" nitrogen)) same etch\$3 not S60	US-PGPU B; USPAT	OR	ON	2005/09/23 02:47
S56	0	S52 and ((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane) with (CH2F2 CF2H2 "CH.sub.2 F.sub.2" "CF.sub.2 H.sub.2" difluoromethane) with (N2 "N.sub.2" nitrogen))	US-PGPU B; USPAT	OR	ON	2005/09/23 02:42
S58	14	S55 S57	US-PGPU B; USPAT	OR	ON	2005/09/23 01:02
S57	5	S52 and ((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane C4F6 "C.sub.4 F.sub.6" perfluorobutadiene octafluorobutadiene C5F8 "C.sub.5 F.sub.8") with (N2 "N.sub.2" nitrogen))	US-PGPU B; USPAT	OR	ON	2005/09/23 01:02
S53	5	S49 and ((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane C4F6 "C.sub.4 F.sub.6" perfluorobutadiene octafluorobutadiene C5F8 "C.sub.5 F.sub.8") with (N2 "N.sub.2" nitrogen))	US-PGPU B; USPAT	OR	ON	2005/09/23 01:02

S55	11	S52 and (((oxygen adj free oxygen-free "without oxygen" "no oxygen") (O2 adj free O2-free "without O2" "no O2") ("O.sub.2" adj free "O.sub.2-free" "without O.sub.2" "no O.sub.2") ("O.sub.2" adj free "O.sub.2-free" "without O.sub.2" "no O.sub.2") ("O2" adj free O2-free "without O2" "no O2")) (dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3)	US-PGPU B; USPAT	OR	ON	2005/09/23 01:01
S51	1	S49 and ((C4F8 "C.sub.4 F.sub.8" perfluorobutane octafluorobutane) with (CH2F2 CF2H2 "CH.sub.2 F.sub.2" "CF.sub.2 H.sub.2" difluoromethane) with (N2 "N.sub.2" nitrogen))	US-PGPU B; USPAT	OR	ON	2005/09/23 01:01
S50	18	S49 and (((oxygen adj free oxygen-free "without oxygen" "no oxygen") (O2 adj free O2-free "without O2" "no O2") ("O.sub.2" adj free "O.sub.2-free" "without O.sub.2" "no O.sub.2") ("O.sub.2" adj free "O.sub.2-free" "without O.sub.2" "no O.sub.2") ("O2" adj free O2-free "without O2" "no O2")) (dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3)	US-PGPU B; USPAT	OR	ON	2005/09/23 01:01

S54	3	S49 and S52	US-PGPU B; USPAT	OR	ON	2005/09/23 00:59
S52	67	("4654112"   "5021121"   "5234537"   "5269879"   "5272115"   "5290383"   "5302236"   "5302240"   "5308742"   "5322590"   "5338399"   "5356515"   "5445710"   "5514247"). PN. OR ("5843847"). URPN.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/09/23 00:52
S47	12	S46 and ((oxygen adj free oxygen-free "without oxygen" "no oxygen") (O2 adj free O2-free "without O2" "no O2") ("O.sub.2" adj free "O.sub.2-free" "without O.sub.2" "no O. sub.2") ("O.sub.2" adj free "O.sub.2-free" "without O. sub.2" "no O.sub.2") ("O2" adj free O2-free "without O2" "no O2"))	US-PGPU B; USPAT	OR	ON	2005/09/23 00:46
S49	89	("4407850"   "4473436"   "4617079"   "4784720"   "4844773"   "4908333"   "4948459"   "4948462"   "4973381"   "4978420"   "4981550"   "5006485"   "5022958").PN. OR ("5269879").URPN.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/09/22 23:45
S48	1	("5269879").PN.	USPAT	OR	OFF	2005/09/22 23:45

S46	162	("20010008226"   "20020038910"   "4349609"   "4654112"   "5021121"   "5234537"   "5242707"   "5262279"   "5269879"   "5272115"   "5290383"   "5302236"   "5302240"   "5308742"   "5322590"   "5338399"   "5356515"   "5445710"   "5468342"   "5514247"   "5562801"   "5679608"   "5698339"   "5783363"   "5877080"   "5911887"   "6016012"   "6074959"   "6114250"   "6127070"   "6180540"   "6204070"   "6204168"   "6204192"   "6207493"   "6211035"   "6211092"   "6221772"   "6228774"   "6232237"   "6284149"   "6316351"   "6326296"   "6372634"   "6475922").PN. OR ("2003/0045101"   "2003/0162407"   "5843847"   "6284149"   "6455411"   "6485988"   "6670276"   "6693042"). URPN.	US-PGPU B; USPAT; USOCR	OR	OFF	2005/09/22 21:11
S45	15	S41 not S42	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:36
S44	18	S42 not S43	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:35

S43	14	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) with etch\$3 same (nitrogen N2 "N.sub.2") with (C4F6 C5F8 C4F8 C6F6 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "C.sub.6 F.sub.6")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:16
S42	32	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) with etch\$3 and (nitrogen N2 "N.sub.2") with (C4F6 C5F8 C4F8 C6F6 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "C.sub.6 F.sub.6")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:07
S41	47	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and etch\$3 and (nitrogen N2 "N.sub.2") with (C4F6 C5F8 C4F8 C6F6 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "C.sub.6 F.sub.6")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:07
S1	288	(low adj k adj dielectric low-k-dielectric low-k adj dielectric ((low adj k low-k) adj material)) and (etch\$3 plasma) and (nitrogen N2 "n.sub.2") and (fluorocarbon hydrofluorocarbon C4F6 C5F8 C4F8 CF2H2 CH2F2 "C.sub.4 F.sub.6" "C.sub.5 F.sub.8" "C.sub.4 F.sub.8" "CF.sub.2 H.sub.2" "CH.sub.2 F.sub.2")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/05/05 13:04
S40	1	("6403491").PN.	USPAT; USOCR	OR	OFF	2004/09/30 00:02



S39	1	(multiple dual) near frequency same mxp	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2004/09/30 00:01
S38	0	(multiple dual) near frequency with mxp	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	OFF	2004/09/29 23:59
S37	11	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3 same (C4F8 "C.sub.4 F.sub.8") with (CH2F2 "CH.sub.2 F.sub.2" CF2H2 "CF.sub.2 H.sub.2") and (nitrogen N2 "N.sub.2"))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 03:05
S36	28	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3 and (C4F8 "C.sub.4 F.sub.8") and (CH2F2 "CH.sub.2 F.sub.2" CF2H2 "CF.sub.2 H.sub.2") and (nitrogen N2 "N.sub.2"))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 03:05

S19	4238	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 02:53
S35	66	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) and etch\$3 same (selectiv\$3 with (mask\$3 overlying)) same (nitrogen N2 "N.sub.2")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:35
S34	3	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) same etch\$3 same (selectiv\$3 with (mask\$3 overlying)) same (nitrogen N2 "N.sub.2")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:33
S33	415	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:32

S32	20	(((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3) and Lam.as.) not (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")) and Lam.as.) (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3) and Lam.as.) (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) same etch\$3) and Lam.as.))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:23
S31	38	((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) and (low-k low adj (dielectric k)) and etch\$3) and Lam.as.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:23

S27	11	((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3) and Lam.as.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:23
S30	7	((((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) same etch\$3) and Lam.as.) not (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3) and Lam.as.) (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")) and Lam.as.))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:17
S29	18	((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) same etch\$3) and Lam.as.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:16

S28	7	(((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3) and Lam.as.) not (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")) and Lam.as.)	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:16
S25	4	((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")) and Lam.as.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/10 00:09

S26	21	((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying))) not (((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2")) ((dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) near2 (low-k low adj (dielectric k)) near2 etch\$3))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 22:02
S24	29	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying)) and (nitrogen N2 "N.sub.2"))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 21:57

S23	51	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3 and (selectiv\$3 with (mask\$3 overlying))	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 21:48
S21	233	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) with (low-k low adj (dielectric k)) with etch\$3	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 21:46
S22	7	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) near2 (low-k low adj (dielectric k)) near2 etch\$3	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 21:33
S20	981	(dop\$3 with ((silicon adj \$2oxide) oxide silicate glass) BPSG PSG (fluorinated fluoro) adj silicon adj \$2oxide FSG CORAL HOSP HSQ) same (low-k low adj (dielectric k)) same etch\$3	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2004/09/09 21:31